

# STP14NF10

### N-channel 100 V - 0.115 Ω - 15 A - TO-220 low gate charge STripFET™ II Power MOSFET

### Features

Туре	V <sub>DSS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>
STP14NF10	100 V	< 0.13 Ω	15 A

- Exceptional dv/dt capability
- 100% avalanche tested
- Application oriented characterization

### Application

Switching applications

### Description

This Power MOSFET series realized with STMicroelectronics unique STripFET<sup>™</sup> process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced highefficiency, high-frequency isolated DC-DC converters for telecom and computer applications. It is also intended for any applications with low gate drive requirements.

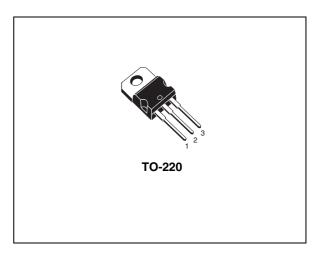
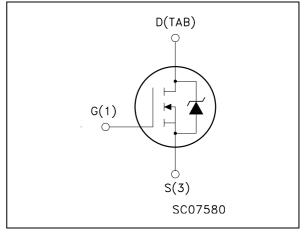


Figure 1. Internal schematic diagram



#### Table 1. Device summary

Order code	Marking	Package	Packaging	
STP14NF10	P14NF10	TO-220	Tube	

## Contents

1	Electrical ratings
2	Electrical characteristics4
	2.1 Electrical characteristics (curves)
3	Test circuits
4	Package mechanical data 9
5	Revision history



### 1

# Electrical ratings

Table 2.	Absolute	maximum	ratings
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Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source voltage ( $V_{GS} = 0$ )	100	V
V <sub>GS</sub>	Gate- source voltage	± 20	V
۱ <sub>D</sub>	Drain current (continuous) at $T_C = 25 \text{ °C}$	15	A
۱ <sub>D</sub>	Drain current (continuous) at $T_C = 100 \text{ °C}$	10	A
I <sub>DM</sub> <sup>(1)</sup>	Drain current (pulsed)	60	A
P <sub>tot</sub>	Total dissipation at $T_C = 25 \ ^{\circ}C$	60	W
	Derating factor	0.4	W/°C
dv/dt <sup>(2)</sup>	Peak diode recovery voltage slope	9	V/ns
E <sub>AS</sub> <sup>(3)</sup>	Single pulse avalanche energy	70	mJ
T <sub>stg</sub>	Storage temperature	-55 to 175	°C
Тj	Max. operating junction temperature	175	°C

1. Pulse width limited by safe operating area.

2. I\_{SD}  $\leq$  14A, di/dt  $\leq$  300A/µs, V\_{DD}  $\leq$  V\_{(BR)DSS}, Tj  $\,\leq$  T\_{JMAX}

3. Starting  $T_j = 25 \text{ °C}$ ,  $I_D = 15A$ ,  $V_{DD} = 50V$ 

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max	2.5	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient max	62.5	°C/W
TJ	Maximum lead temperature for soldering purpose	300	°C



# 2 Electrical characteristics

(T<sub>CASE</sub>=25 °C unless otherwise specified)

	On/on states					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0$	100			V
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	$V_{DS}$ = max ratings $V_{DS}$ = max ratings, $T_{C}$ = 125 °C			1 10	μΑ μΑ
I <sub>GSS</sub>	Gate-body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS}=V_{GS},\ I_{D}=250\ \mu A$	2	3	4	V
R <sub>DS(on)</sub>	Static drain-source on resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7 A		0.115	0.13	Ω

#### Table 4. On/off states

#### Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 <sub>fs</sub> <sup>(1)</sup>	Forward transconductance	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 7 A		20		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input capacitance Output capacitance Reverse transfer capacitance	V <sub>DS</sub> = 25 V, f = 1 MHz, V <sub>GS</sub> = 0		460 70 30		pF pF pF
t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD} = 50 \text{ V}, I_D = 7 \text{ A}$ $R_G = 4.7 \Omega V_{GS} = 10 \text{ V}$ (see <i>Figure 14</i> )		16 25 32 8		ns ns ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 80 V, I_D = 12 A,$ $V_{GS} = 10 V$ (see <i>Figure 15</i> )		15.5 3.7 4.7	21	nC nC nC

1. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5%.



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current Source-drain current (pulsed)				15 60	A A
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	I <sub>SD</sub> = 14 A, V <sub>GS</sub> = 0			1.5	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 14 \text{ A},$ di/dt = 100 A/µs, $V_{DD} = 50 \text{ V}, \text{ T}_{j} = 150 ^{\circ}\text{C}$ (see <i>Figure 16</i> )		90 230 5		ns nC A

Table 6.Source drain diode

1. Pulse width limited by safe operating area.

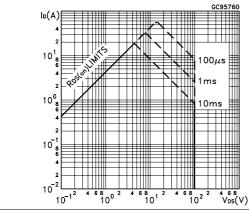
2. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5%

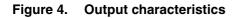


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### 2.1 Electrical characteristics (curves)

#### Figure 2. Safe operating area





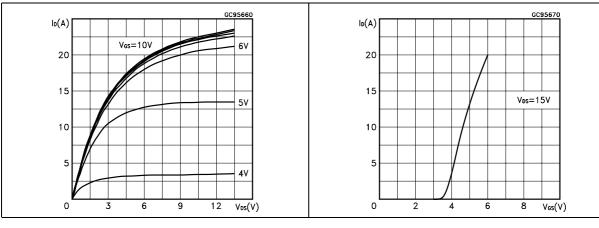


Figure 3.

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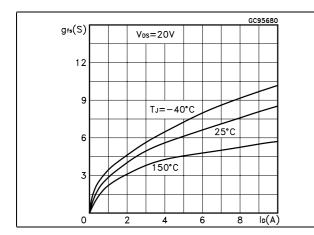
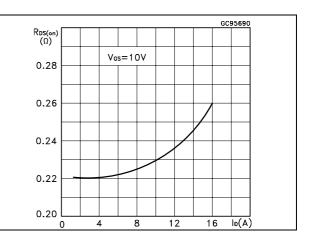
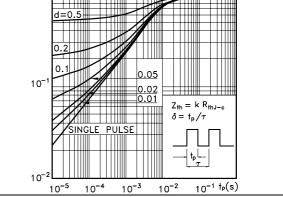


Figure 7. Static drain-source on resistance

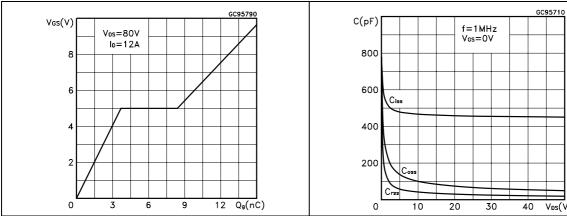




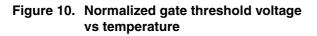




**Thermal impedance** 



#### Gate charge vs gate-source voltage Figure 9. Figure 8. **Capacitance variations**



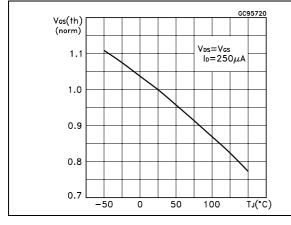


Figure 12. Source-drain diode forward characteristics

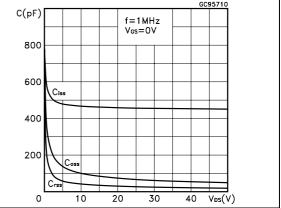


Figure 11. Normalized on resistance vs temperature

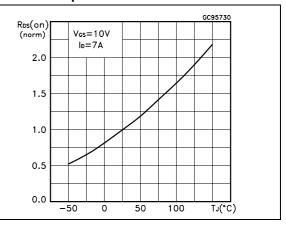
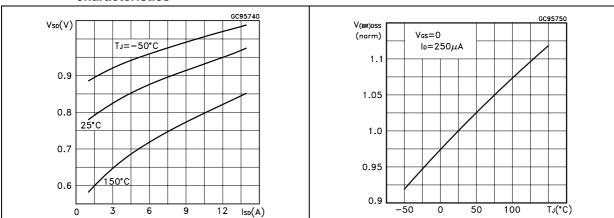


Figure 13. Normalized B<sub>VDSS</sub> vs temperature



57

57

### 3 Test circuits

Figure 14. Switching times test circuit for resistive load

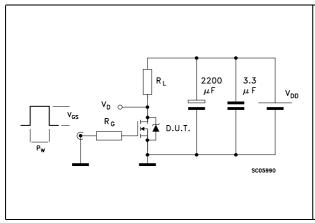
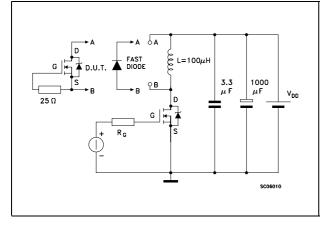


Figure 16. Test circuit for inductive load switching and diode recovery times





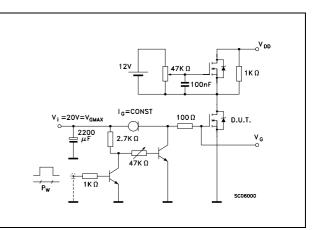


Figure 15. Gate charge test circuit

Figure 17. Unclamped Inductive load test circuit

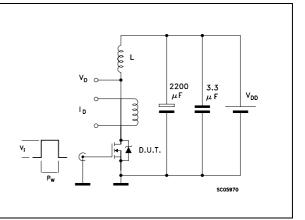
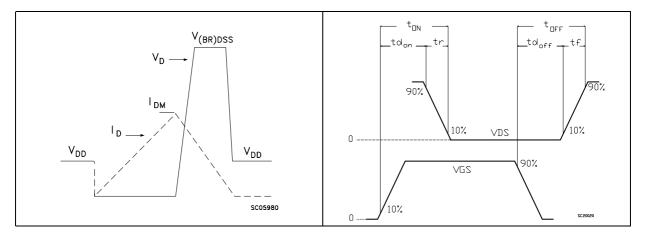


Figure 19. Switching time waveform



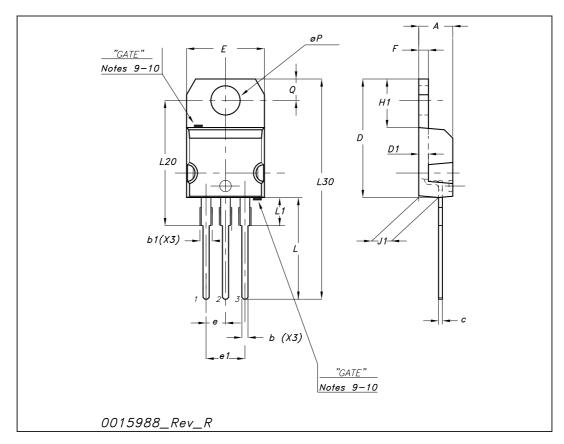
### 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com



57

Dim		mm			inch	
Dill	Min	Тур	Мах	Min	Тур	Max
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
С	0.48		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
ØP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



# 5 Revision history

#### Table 7. Document revision history

Date	Revision	Changes
05-Feb-2004	1	First version
21-Jun-2004	2	Preliminary version
19-Jun-2006	3	New template, no content change
20-Mar-2008	4	Removed packages: D <sup>2</sup> PAK and TO-220FP



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